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AMENDMENT UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 1775  
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q67726

Mitsuo OSADA, et al.

Appn. No.: 10/009,822

Group Art Unit: 1775

Confirmation No.: 6202

Examiner: Michael E. Lavilla

Filed: December 13, 2001

For: MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC PACKAGE USING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.116

MAIL STOP AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated March 29, 2005, please amend the above-identified application as follows on the accompanying pages.

for me  
my  
7/29/05  
L.C.H.  
8/3/05  
AMC-F  
Entered per  
R.C. dated  
7/29/05